

Ultra High Performance BGA Cooling Solutions w/ maxiGRIP[™] Attachment

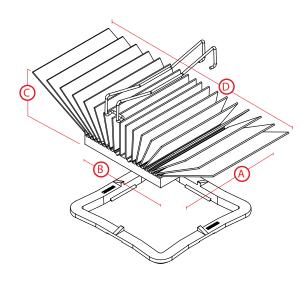
ATS PART # ATS-51400K-C2-R0

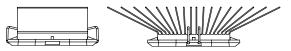
Features & Benefits

- maxiFLOW[™] design features a low profile, spread fin » array that maximizes surface area for more effective convection (air) cooling
- maxiGRIP[™] attachment applies steady, even pressure to » the component and does not require holes in the PCB
- Meets Telcordia GR-63-Core Office Vibration; ETSI 300 » 019 Transportation Vibration; and MIL-STD-810 Shock and Unpackaged Drop Testing standards
- Comes preassembled with high performance thermal » interface material

Thermal Performance

Designed for low profile components from 1.5 to 2.99mm »





*Image above is for illustration purposes only.

AIR VELOCITY				THERMAL RESISTANCE		
	FT/MIN M/S		I/S	°C/W (UNDUCTED FLOW)	°C/W (DUCTED FLOW)	
	200	1	.0	2.5	1.9	
	300	1	.5	2		
	400	2	.0	1.7		
500		2.5		1.5		
600		3.0		1.4		
700		3	.5	1.3		
800		4	.0	1.2		

Product Details

DIMENSION A	DIMENSION B	DIMENSION C	DIMENSION D	INTERFACE MATERIAL	FINISH
40 mm	40 mm	14.5 mm	69.2 mm	SAINT-GOBAIN C675	BLACK- ANODIZED

NOTES:

2) Thermal performance data are provided for reference only. Actual performance may vary

by application.

- ATS reserves the right to update or change its products without notice to improve the 3) design or performance.
- 4) Optional maxiGRIP™ Installation/Removal Tool Set P/N: MGT400
- 5) Contact ATS to learn about custom options available.



For more information, to find a distributor or to place an order, visit www.gats.com or call: 781.769.2800 (North America); +31 (0) 3569 84715 (Europe).

Dimension C = heat sink height from bottom of the base to the top of the fin field.